

PATENT ABSTRACTS OF JAPAN

(11) Publication number : 09-213838
 (43) Date of publication of application : 15.08.1997

(51) Int.CI.

H01L 23/12

(21) Application number : 08-038985
 (22) Date of filing : 31.01.1996

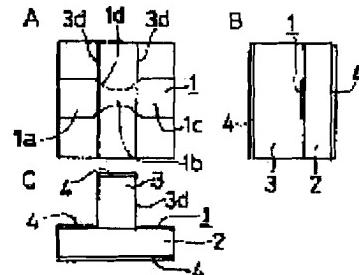
(71) Applicant : SUMITOMO ELECTRIC IND LTD
 (72) Inventor : TATO NOBUYOSHI
 NISHI KOJI

(54) TERMINAL OF SEMICONDUCTOR RECEPTACLE AND SEMICONDUCTOR AIRTIGHTLY SEALED RECEPTACLE

(57) Abstract:

PROBLEM TO BE SOLVED: To reduce a reflection loss even at a high frequency to enhance a degree of freedom for mounting by making the shape of the layer surface of a wiring comprising a metallized layer for transmitting an electric signal into a strip-like form having a narrow width at the central part to moderately form the boundary between the narrow part and the wide part without perpendicularly crossing them.

SOLUTION: A conductive metallized layer 4 is formed in the lower surface of an insulating body 2. In the upper surface, the metallized layer 4 forming a wiring 1 is formed so that it is made in a strip-like form and that the width of the central part 1b is made narrower than the width of both sides 1a, 1c and the boundary having a different width is moderately linked together by a sloping line 1d. Thus, since it is moderately formed of a sloping line and a curve without perpendicularly crossing each other, wraparound is corrected. Also, an electric field concentrated into the top of the conventional rectangle is relaxed. Further, on the other hand, a part which does not come into contact with the insulating body 2 is formed in both surfaces of the metallized layer 4, whereby soldering, gold pressure connection or the like between the other insulating body and the thin film metallized layer 4 can be easily performed from that part.



LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

Copyright (C); 1998,2000 Japan Patent Office